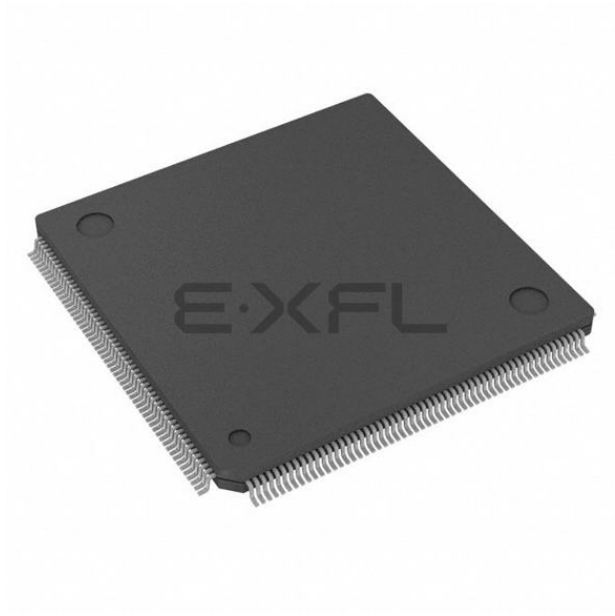

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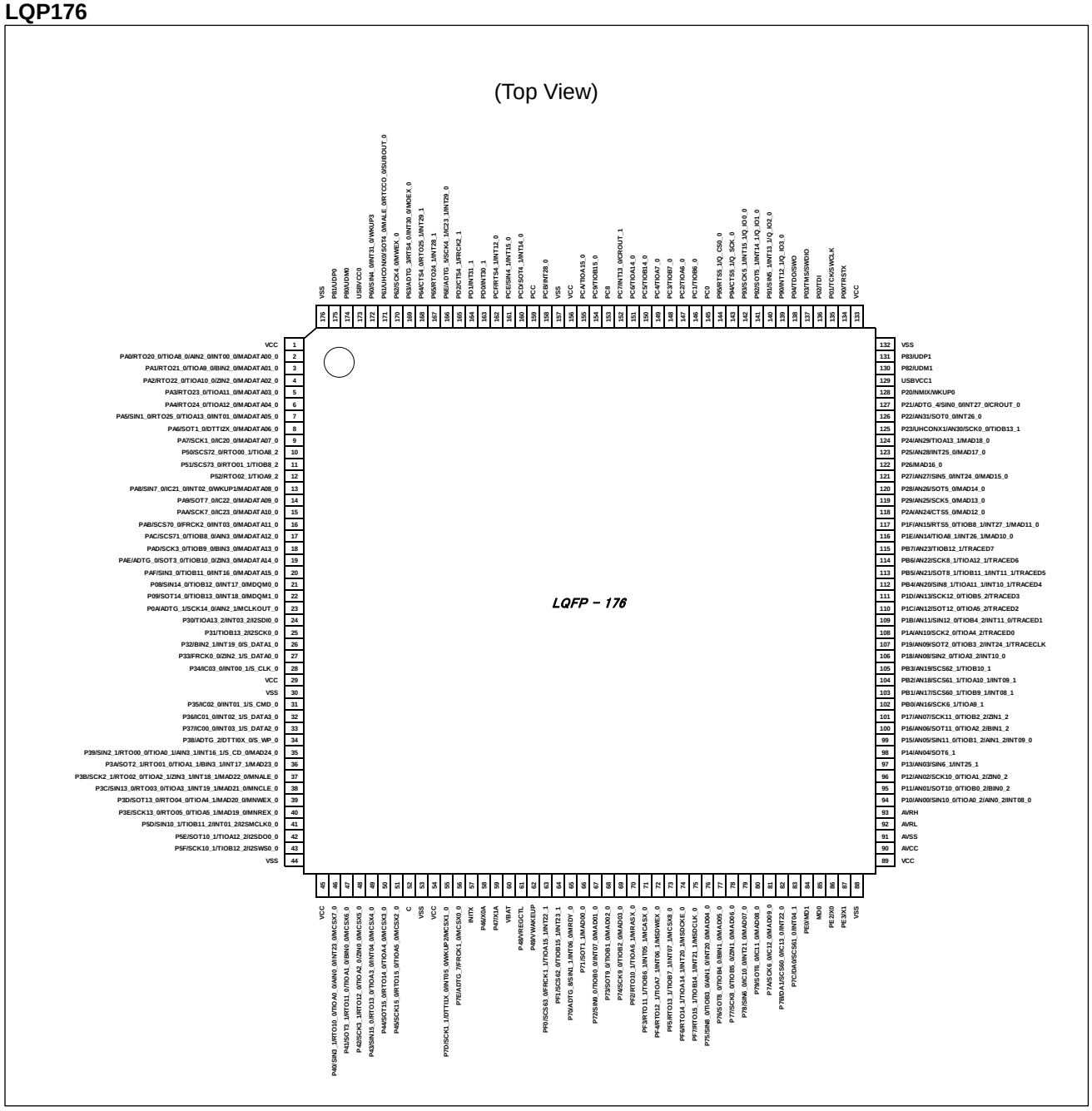
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CSIO, EBI/EMI, I²C, LINbus, SD, SPI, UART/USART, USB
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	190
Program Memory Size	1.5MB (1.5M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	216-LQFP
Supplier Device Package	216-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2c39l0agl2000a

LQP176



Note:

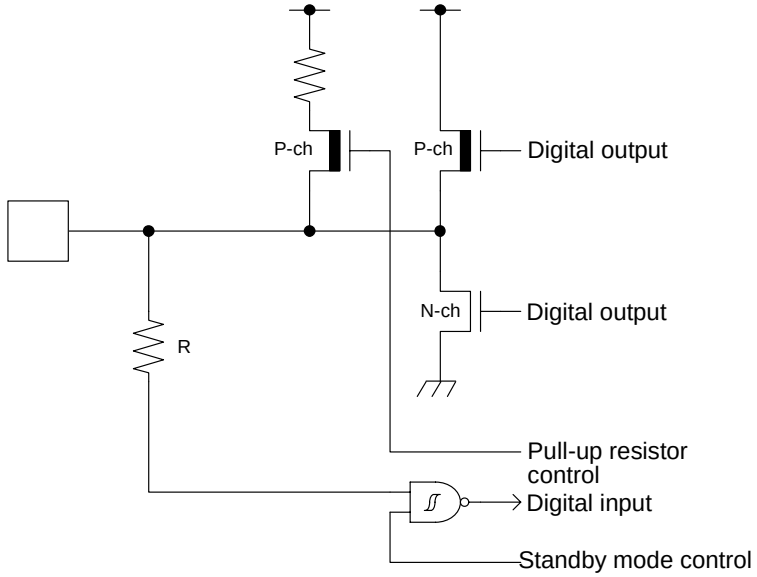
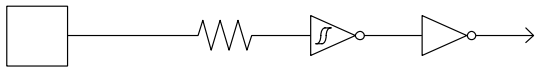
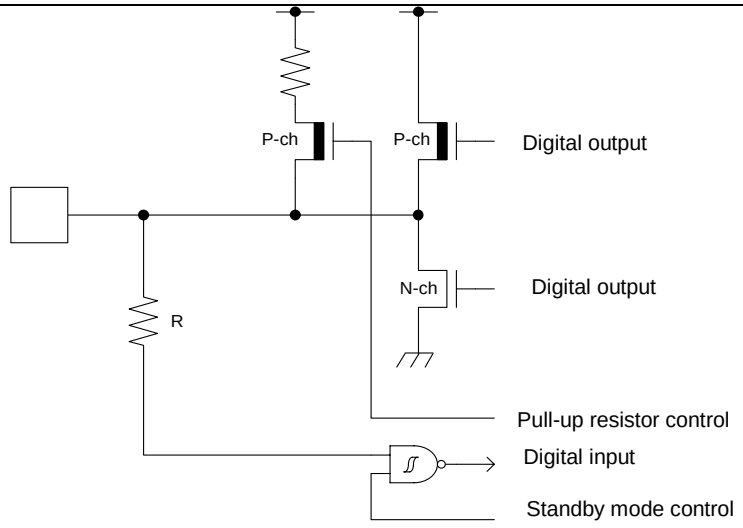
- *The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel. Use the extended port function register (EPFR) to select the pin.*

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Base Timer 13	TIOA13_0	Base Timer ch 13 TIOA pin	7	7	7	D1
	TIOA13_1		154	124	100	E12
	TIOA13_2		34	24	-	G6
	TIOB13_0	Base Timer ch 13 TIOB pin	31	22	19	G4
	TIOB13_1		155	125	101	E13
	TIOB13_2		35	25	-	H4
Base Timer 14	TIOA14_0	Base Timer ch 14 TIOA pin	183	151	121	D8
	TIOA14_1		89	74	-	M9
	TIOA14_2		204	-	-	-
	TIOB14_0	Base Timer ch 14 TIOB pin	182	150	120	C8
	TIOB14_1		90	75	-	L9
	TIOB14_2		203	-	-	-
Base Timer 15	TIOA15_0	Base Timer ch 15 TIOA pin	187	155	125	B7
	TIOA15_1		78	63	-	K5
	TIOA15_2		206	-	-	-
	TIOB15_0	Base timer ch 15 TIOB pin	186	154	124	F8
	TIOB15_1		79	64	-	K6
	TIOB15_2		205	-	-	-
Debugger	SWCLK	Serial wire debug interface clock input pin	165	135	111	A12
	SWDIO	Serial wire debug interface data input/ output pin	167	137	113	B12
	SWO	Serial wire viewer output pin	168	138	114	B11
	TCK	JTAG test clock input pin	165	135	111	A12
	TDI	JTAG test data input pin	166	136	112	C12
	TDO	JTAG debug data output pin	168	138	114	B11
	TMS	JTAG test mode state input/output pin	167	137	113	B12
	TRACECLK	Trace CLK output pin of ETM/HTM	131	107	87	H12
	TRACED0	Trace data output pin of ETM/ Trace data output pin of HTM	132	108	88	H14
	TRACED1		133	109	89	G14
	TRACED2		134	110	90	H13
	TRACED3		135	111	91	H11
	TRACED4	Trace data output pin of HTM	138	112	-	G13
	TRACED5		139	113	-	F14
	TRACED6		140	114	-	G12
	TRACED7		141	115	-	G11
	TRACED8		119	-	-	-
	TRACED9		120	-	-	-
	TRACED10		121	-	-	-
	TRACED11		122	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
GPIO	P70	General-purpose I/O port 7	80	65	55	L6
	P71		81	66	56	J6
	P72		82	67	57	L8
	P73		83	68	58	K8
	P74		84	69	59	J8
	P75		91	76	60	K9
	P76		92	77	61	P10
	P77		93	78	62	N10
	P78		96	79	63	L10
	P79		97	80	64	K10
	P7A		98	81	65	M10
	P7B		99	82	66	N11
	P7C		100	83	67	M11
	P7D		70	55	47	L5
	P7E		71	56	48	M5
	P80	General-purpose I/O port 8	214	174	142	A3
	P81		215	175	143	A2
	P82		160	130	106	D14
	P83		161	131	107	C14
	P90	General-purpose I/O port 9	169	139	-	C11
	P91		170	140	-	D11
	P92		171	141	-	B10
	P93		172	142	-	C10
	P94		173	143	-	D10
	P95		174	144	-	B9
	P96		175	-	-	-
	P97		176	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
Quadrature Position/ Revolution Counter 0	AIN0_0	QPRC ch 0 AIN input pin	56	46	38	N2
	AIN0_1		65	-	-	-
	AIN0_2		114	94	78	L11
	BIN0_0	QPRC ch 0 BIN input pin	57	47	39	N3
	BIN0_1		66	-	-	-
	BIN0_2		115	95	79	K13
	ZIN0_0	QPRC ch 0 ZIN input pin	58	48	40	M3
	ZIN0_1		67	-	-	-
	ZIN0_2		116	96	80	K12
Quadrature Position/ Revolution Counter 1	AIN1_0	QPRC ch 1 AIN input pin	91	76	60	K9
	AIN1_1		94	-	-	-
	AIN1_2		123	99	83	J13
	BIN1_0	QPRC ch 1 BIN input pin	92	77	61	P10
	BIN1_1		45	-	-	-
	BIN1_2		124	100	84	J12
	ZIN1_0	QPRC ch 1 ZIN input pin	93	78	62	N10
	ZIN1_1		101	-	-	-
	ZIN1_2		125	101	85	J11
Quadrature Position/ Revolution Counter 2	AIN2_0	QPRC ch 2 AIN input pin	2	2	2	B2
	AIN2_1		32	23	20	G5
	AIN2_2		120	-	-	-
	BIN2_0	QPRC ch 2 BIN input pin	3	3	3	C2
	BIN2_1		36	26	21	H2
	BIN2_2		121	-	-	-
	ZIN2_0	QPRC ch 2 ZIN input pin	4	4	4	C3
	ZIN2_1		37	27	22	J1
	ZIN2_2		122	-	-	-
Quadrature Position/ Revolution Counter 3	AIN3_0	QPRC ch 3 AIN input pin	18	17	14	F4
	AIN3_1		45	35	30	J2
	AIN3_2		149	-	-	-
	BIN3_0	QPRC ch 3 BIN input pin	23	18	15	F5
	BIN3_1		46	36	31	K1
	BIN3_2		150	-	-	-
	ZIN3_0	QPRC ch 3 ZIN input pin	24	19	16	F6
	ZIN3_1		47	37	32	K2
	ZIN3_2		151	-	-	-

Module	Pin Name	Function	Pin Number			
			LQQ 216	LQP 176	LQS 144	LBE 192
I²S	I2SMCLK0_0	I²S external clock pin	51	41	-	L2
	I2SDO0_0	I²S serial transition data output pin	52	42	-	L3
	I2SWS0_0	I²S frame synchronization signal pin	53	43	-	M2
	I2SDI0_0	I²S serial received data input pin	34	24	-	G6
	I2SCK0_0	I²S bit clock pin	35	25	-	H4
High-speed quad SPI	Q_SCK_0	SPI clock output pin	173	143	-	D10
	Q_IO0_0	SPI data input/output pin	172	142	-	C10
	Q_IO1_0		171	141	-	B10
	Q_IO2_0		170	140	-	D11
	Q_IO3_0		169	139	-	C11
	Q_CS0_0	SPI chip select output pin	174	144	-	B9
	Q_CS1_0		175	-	-	-
	Q_CS2_0		176	-	-	-

Type	Circuit	Remarks
I		・ CMOS level output ・ CMOS level hysteresis input ・ 5V tolerant ・ Pull-up resistor control ・ Standby mode control ・ Pull-up resistor: approximately 50 kΩ ・ I_{OH} = -4 mA, I_{OL} = 4 mA ・ Available to control of PZR registers (pseudo-open drain control) ・ For PZR registers, refer to GPIO in the “FM4 Family Peripheral Manual Main Part (002-04856)”.
J		CMOS level hysteresis input
K		・ CMOS level output ・ TTL level hysteresis input ・ Pull-up resistor control ・ Standby mode control ・ Pull-up resistor: approximately 50 kΩ ・ I_{OH} = -4mA, I_{OL} = 4mA

6. Handling Precautions

Every semiconductor device has a characteristic, inherent rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

6.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

Processing and Protection of Pins

These precautions must be followed when handling the pins that connect semiconductor devices to power supply and I/O functions.

1. Preventing Over-Voltage and Over-Current Conditions

   Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.
2. Protection of Output Pins

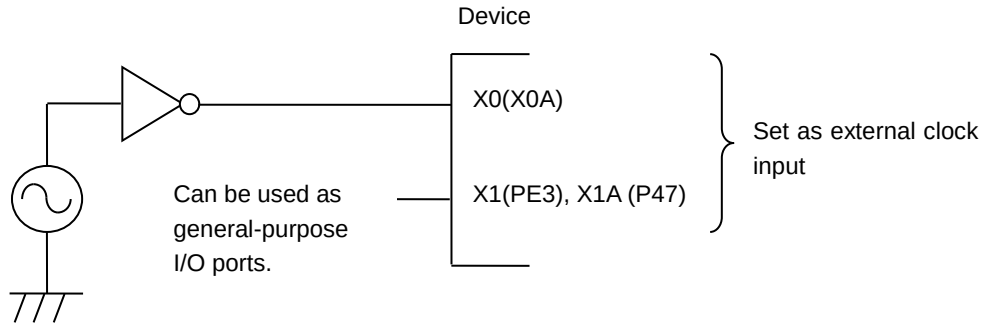
   Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions, if present for extended periods of time, can damage the device; therefore, avoid this type of connection.
3. Handling of Unused Input Pins

   Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power-supply pin or ground pin.

Using an External Clock

When using an external clock as an input of the main clock, set X0/X1 to the external clock input, and input the clock to X0. X1(PE3) can be used as a general-purpose I/O port. Similarly, when using an external clock as an input of the sub clock, set X0A/X1A to the external clock input and input the clock to X0A. X1A (P47) can be used as a general-purpose I/O port.

● Example of Using an External Clock

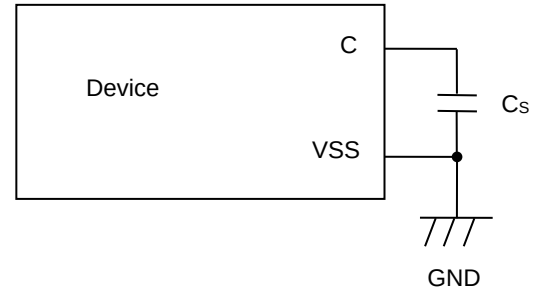


Handling When Using Multi-Function Serial Pin as I²C Pin

If the application uses the multi-function serial pin as an I²C pin, the P-channel transistor of the digital output must be disabled. I²C pins need to conform to electrical limitations like other pins, however, and avoid connecting to live external systems with the MCU power off.

C Pin

Devices in this series contain a regulator. Be sure to connect a smoothing capacitor (C_S) for the regulator between the C pin and the GND pin. Please use a ceramic capacitor or a capacitor of equivalent frequency characteristics as a smoothing capacitor. Some laminated ceramic capacitors have a large capacitance variation due to thermal fluctuation. Please select a capacitor that meets the specifications in the operating conditions to use by evaluating the temperature characteristics of the device. A smoothing capacitor of about 4.7 µF would be recommended for this series.



Mode Pins (MD0)

Connect the MD pin (MD0) directly to VCC or VSS pins. Design the printed circuit board such that the pull-up/down resistance stays low, the distance between the mode pins and VCC pins or VSS pins is as short as possible, and the connection impedance is low when the pins are pulled up/down such as for switching the pin level and rewriting the flash memory data. This is important to prevent the device from erroneously switching to test mode as a result of noise.

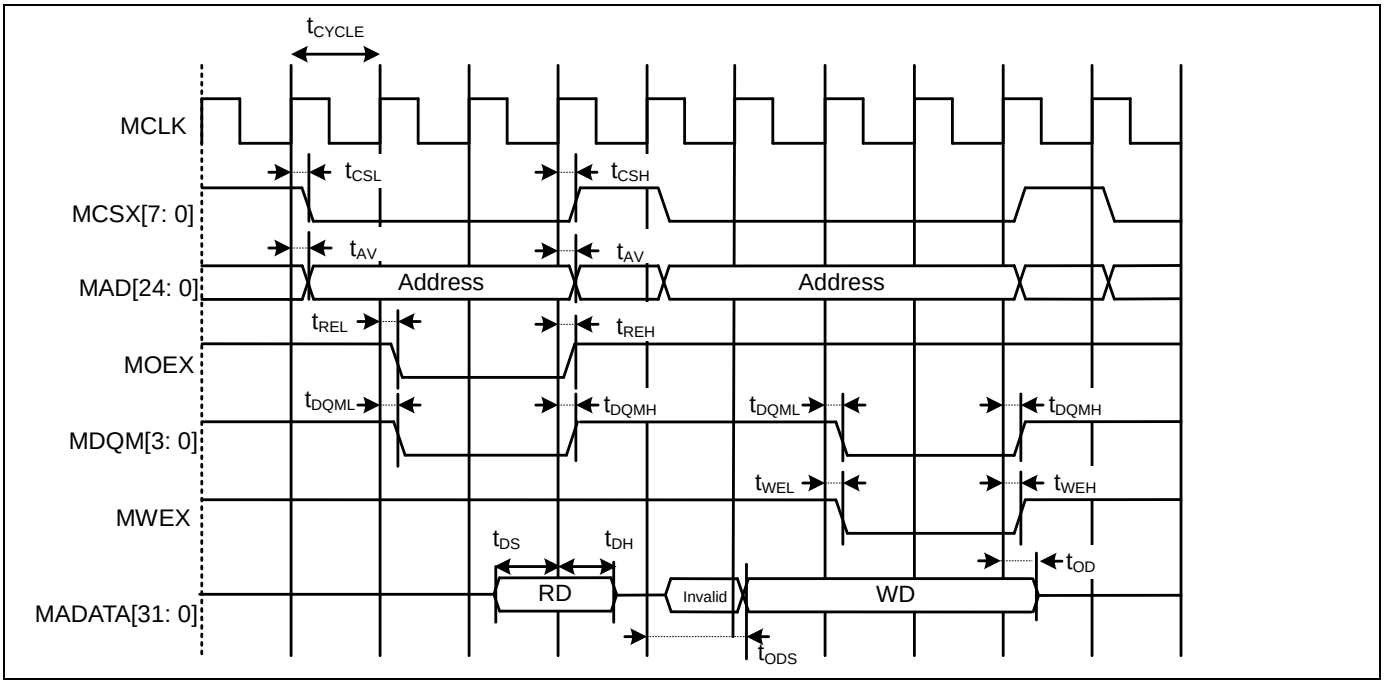
Separate Bus Access Synchronous SRAM Mode

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

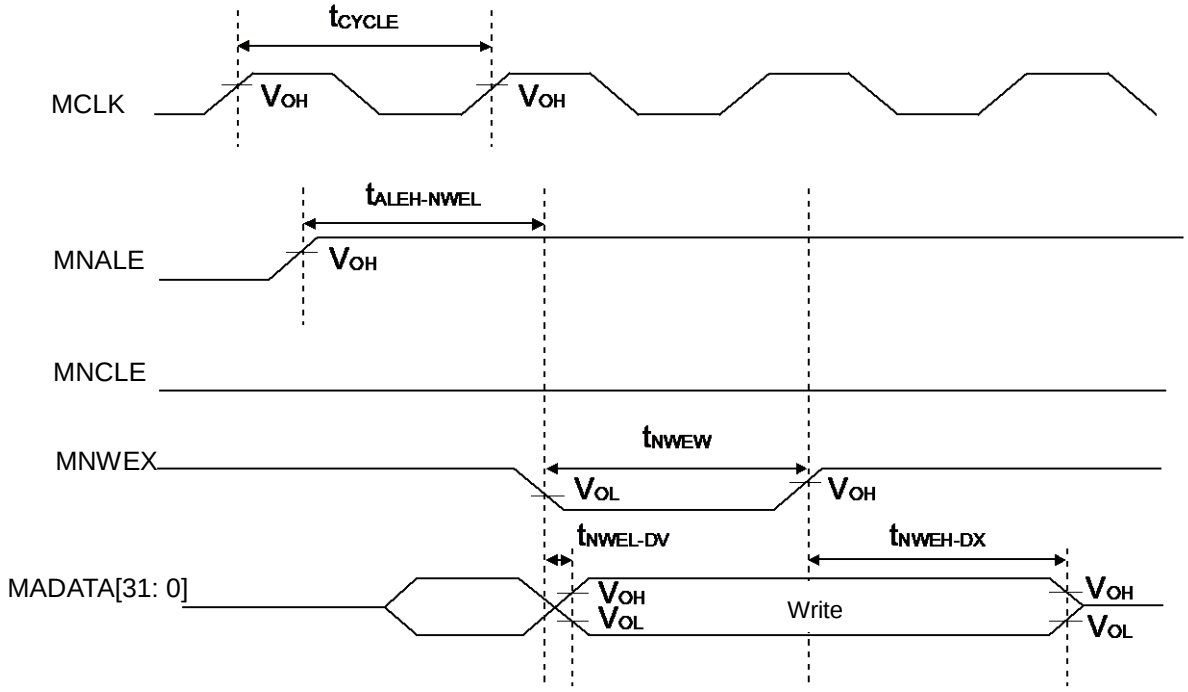
Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Address delay time	t_{AV}	MCLK, MAD[24: 0]	-	1	9	ns	
MCSX delay time	t_{CSL}	MCLK, MCSX[7: 0]	-	1	9	ns	
	t_{CSH}		-	1	9	ns	
MOEX delay time	t_{REL}	MCLK, MOEX	-	1	9	ns	
	t_{REH}		-	1	9	ns	
Data set up →MCLK ↑ time	t_{DS}	MCLK, MADATA[31: 0]	-	19	-	ns	
MCLK ↑ → Data hold time	t_{DH}	MCLK, MADATA[31: 0]	-	0	-	ns	
MWEX delay time	t_{WEL}	MCLK, MWEX	-	1	9	ns	
	t_{WEH}		-	1	9	ns	
MDQM[1: 0] delay time	t_{DQML}	MCLK, MDQM[3: 0]	-	1	9	ns	
	t_{DQMH}		-	1	9	ns	
MCLK ↑ → Data output time	t_{ODS}	MCLK, MADATA[31: 0]	-	MCLK+1	MCLK+18	ns	
MCLK ↑ → Data hold time	t_{OD}	MCLK, MADATA[31: 0]	-	1	18	ns	

Note:

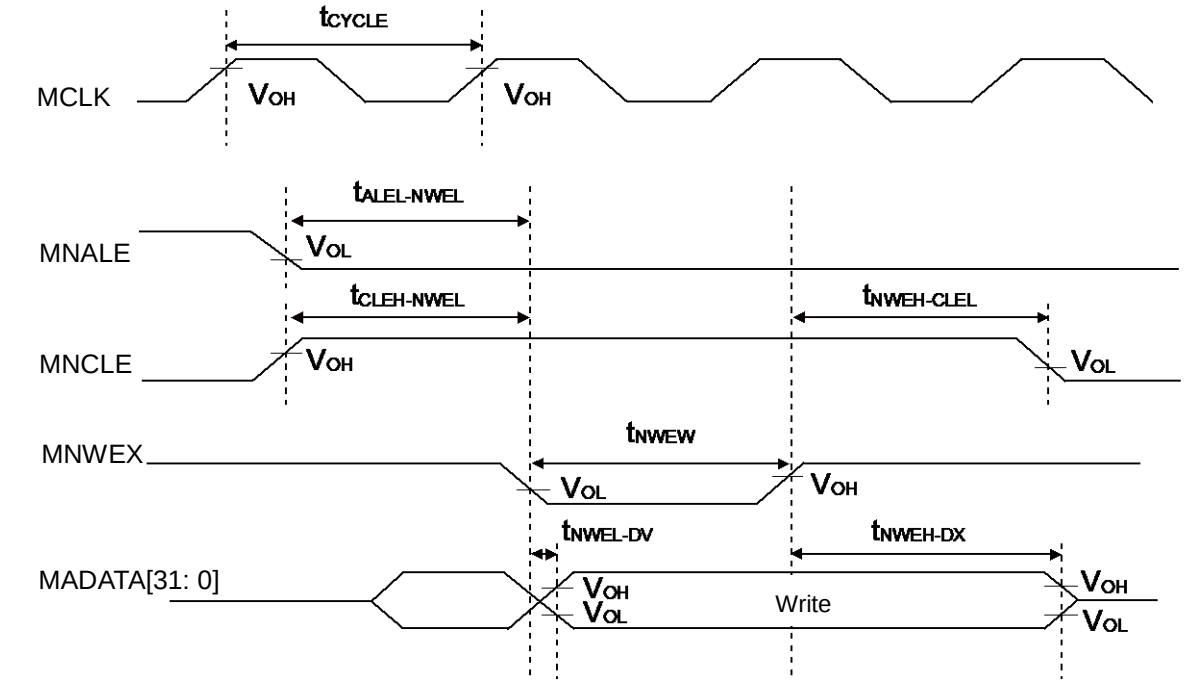
- *When the external load capacitance C_L = 30 pF*



NAND Flash Address Write



NAND Flash Command Write



12.4.12 CSIO (SPI) Timing

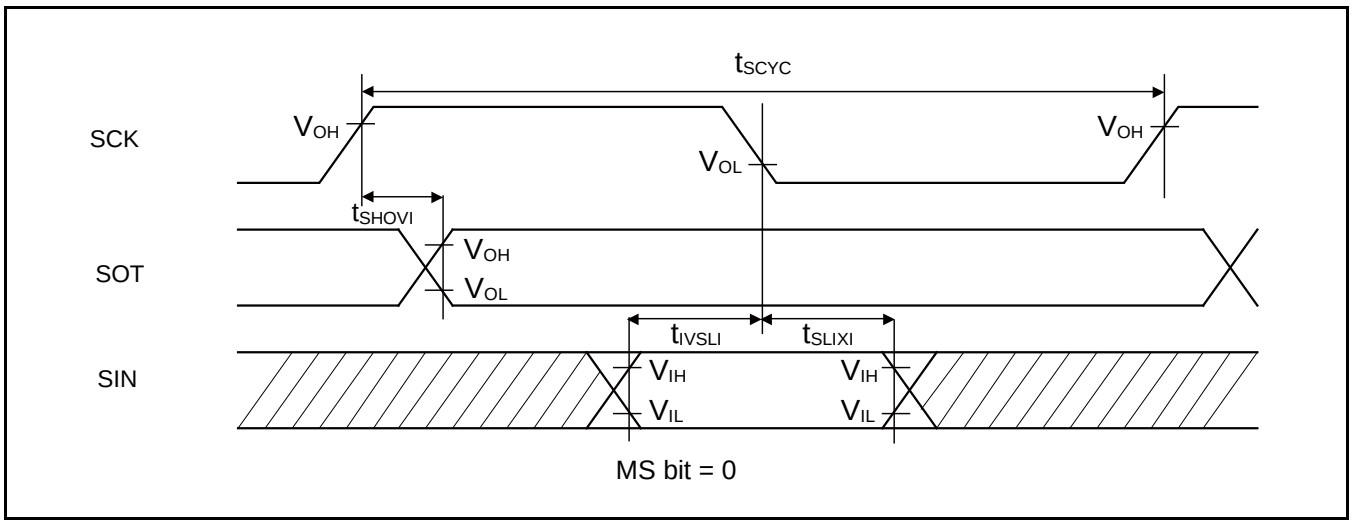
Synchronous Serial (SPI = 0, SCINV = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

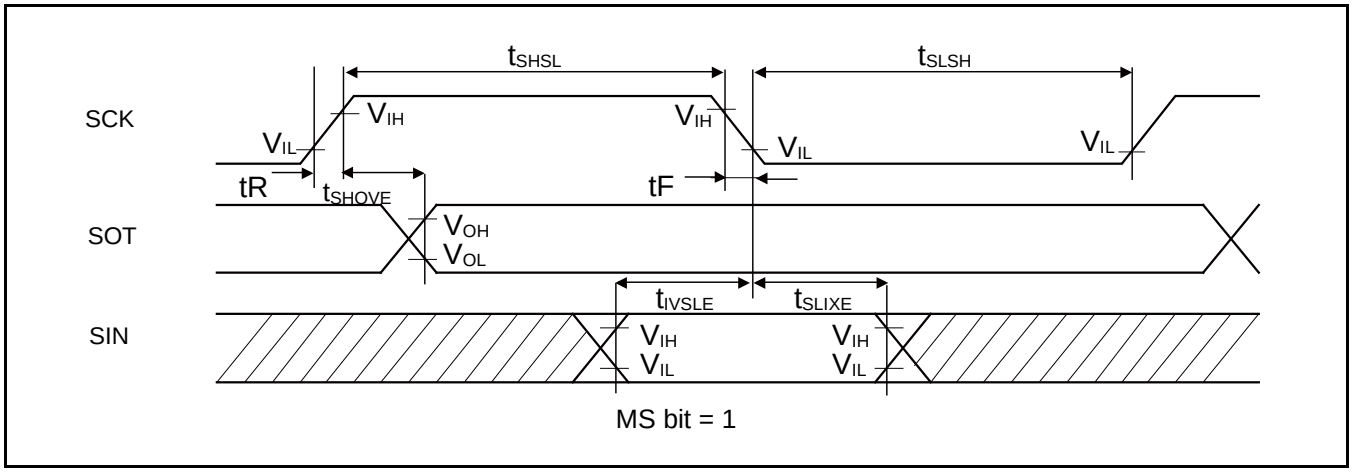
Parameter	Symbol	Pin Name	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Baud rate	-	-		-	8	-	8	Mbps
Serial clock cycle time	t_{SCYC}	SCKx	Internal shift clock operation	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK↓→SOT delay time	t_{SLOVI}	SCKx, SOTx		- 30	+ 30	- 20	+ 20	ns
SIN→SCK↑ setup time	t_{IVSHI}	SCKx, SINx		50	-	30	-	ns
SCK↑→SIN hold time	t_{SHIXI}	SCKx, SINx		0	-	0	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	External shift clock operation	$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK↓→SOT delay time	t_{SLOVE}	SCKx, SOTx		-	50	-	30	ns
SIN→SCK↑ setup time	t_{IVSHE}	SCKx, SINx		10	-	10	-	ns
SCK↑→SIN hold time	t_{SHIXE}	SCKx, SINx		20	-	20	-	ns
SCK fall time	tF	SCKx		-	5	-	5	ns
SCK rise time	tR	SCKx		-	5	-	5	ns

Notes:

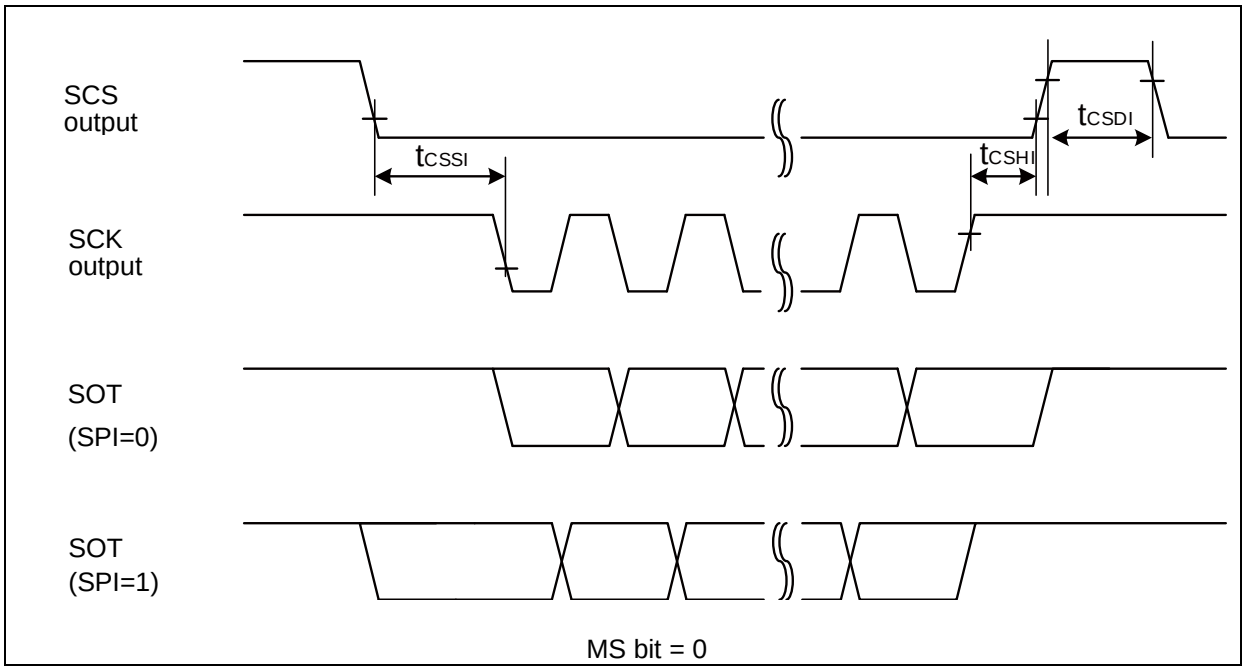
- *The above characteristics apply to CLK synchronous mode.*
- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *These characteristics only guarantee the same relocate port number; for example, the combination of SCKx_0 and SOTx_1 is not guaranteed.*
- *When the external load capacitance C_L = 30 pF.*



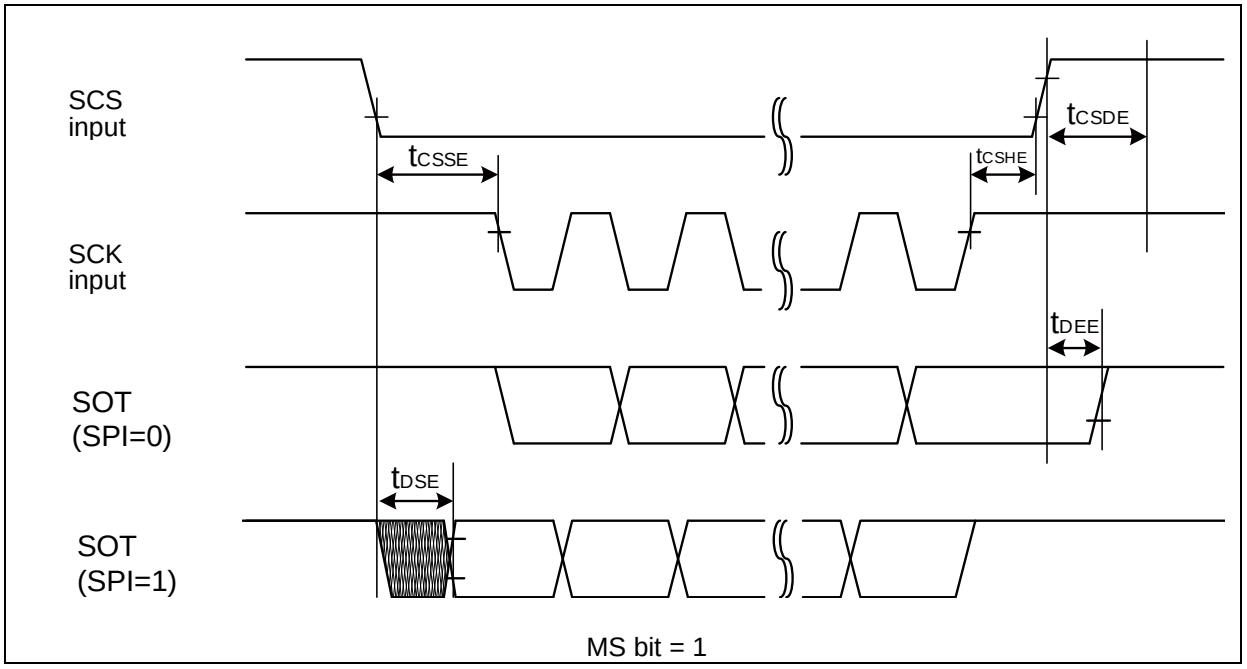
MS bit = 0



MS bit = 1



MS bit = 0



MS bit = 1

High-Speed Synchronous Serial (SPI = 1, SCINV = 0)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	V_{CC} < 4.5 V		V_{CC} ≥ 4.5 V		Unit
				Min	Max	Min	Max	
Serial clock cycle time	t_{SCYC}	SCKx	Internal shift clock operation	$4t_{CYCP}$	-	$4t_{CYCP}$	-	ns
SCK↑→SOT delay time	t_{SHOVI}	SCKx, SOTx		- 10	+ 10	- 10	+ 10	ns
SIN→SCK↓ setup time	t_{IVSLI}	SCKx, SINx		14 12.5*	-	12.5	-	ns
SCK↓→SIN hold time	t_{SLIXI}	SCKx, SINx		5	-	5	-	ns
SOT→SCK↓ delay time	t_{SOVLI}	SCKx, SOTx		$2t_{CYCP}$ - 10	-	$2t_{CYCP}$ - 10	-	ns
Serial clock L pulse width	t_{SLSH}	SCKx	External shift clock operation	$2t_{CYCP}$ - 5	-	$2t_{CYCP}$ - 5	-	ns
Serial clock H pulse width	t_{SHSL}	SCKx		t_{CYCP} + 10	-	t_{CYCP} + 10	-	ns
SCK↑→SOT delay time	t_{SHOVE}	SCKx, SOTx		-	15	-	15	ns
SIN→SCK↓ setup time	t_{IVSLE}	SCKx, SINx		5	-	5	-	ns
SCK↓→SIN hold time	t_{SLIXE}	SCKx, SINx		5	-	5	-	ns
SCK fall time	tF	SCKx		-	5	-	5	ns
SCK rise time	tR	SCKx		-	5	-	5	ns

Notes:

- *The above characteristics apply to CLK synchronous mode.*
- *t_{CYCP} indicates the APB bus clock cycle time. For more information about the APB bus number to which the multi-function serial is connected, see 8. Block Diagram in this data sheet.*
- *These characteristics only guarantee the following pins:*

  No chip select: SIN4_0, SOT4_0, SCK4_0

  Chip select: SIN6_0, SOT6_0, SCK6_0, SCS60_0, SCS61_0, SCS62_0, SCS63_0
- *When the external load capacitance C_L = 30 pF. (for *, when C_L = 10 pF)*

12.4.16 SD Card Interface Timing

Default-Speed Mode

■Clock CLK (All values are referenced to V_{IH} and V_{IL} transition points)

(V_{CC} = 2.7V to 3.6V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Remarks
				Min	Max	
Clock frequency Data Transfer Mode	f_{PP}	S_CLK	C_{CARD} ≤ 10 pF (1card)	0	25	MHz
Clock frequency Identification Mode	f_{OD}	S_CLK		0/100	400	kHz
Clock low time	t_{WL}	S_CLK		10	-	ns
Clock high time	t_{WH}	S_CLK		10	-	ns
Clock rise time	t_{TLH}	S_CLK		-	10	ns
Clock fall time	t_{THL}	S_CLK		-	10	ns

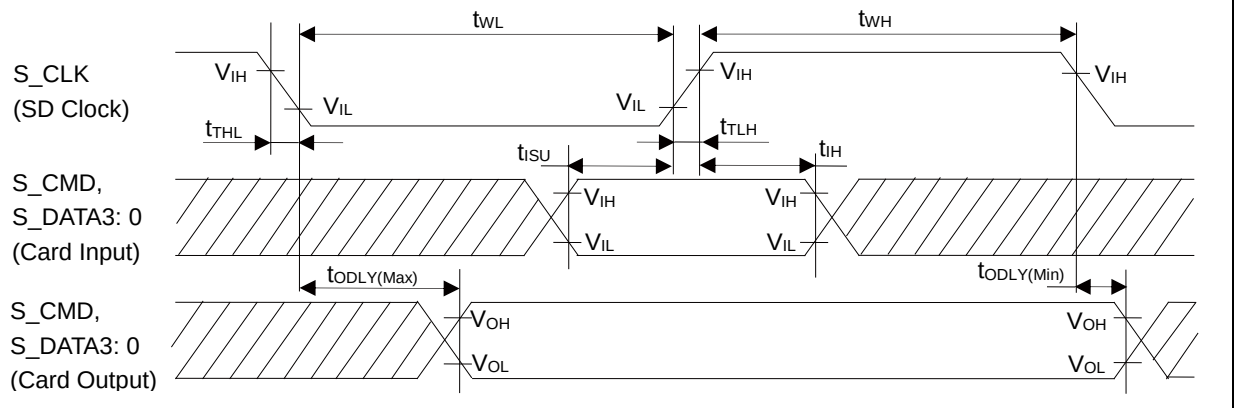
* 0 Hz means to stop the clock. The given minimum frequency range is for cases where a continuous clock is required.

■Card Inputs CMD, DAT (referenced to Clock CLK)

Parameter	Symbol	Pin Name	Conditions	Value		Remarks
				Min	Max	
Input set-up time	t_{ISU}	S_CMD, S_DATA3: 0	C_{CARD} ≤ 10 pF (1card)	5	-	ns
Input hold time	t_{IH}	S_CMD, S_DATA3: 0		5	-	ns

■Card Outputs CMD, DAT (referenced to Clock CLK)

Parameter	Symbol	Pin Name	Conditions	Value		Remarks
				Min	Max	
Output Delay time during Data Transfer Mode	t_{ODLY}	S_CMD, S_DATA3: 0	C_{CARD} ≤ 40 pF (1card)	0	14	ns
Output Delay time during Identification Mode	t_{ODLY}	S_CMD, S_DATA3: 0		0	50	ns



Default-Speed Mode

Notes:

- *The Card Input corresponds to the Host Output and the Card Output corresponds to the Host Input because this model is the Host.*
- *For more information about clock frequency (f_{PP}), see Chapter 15: SD card Interface in FM4 Family Peripheral Manual Main Part (002-04856).*

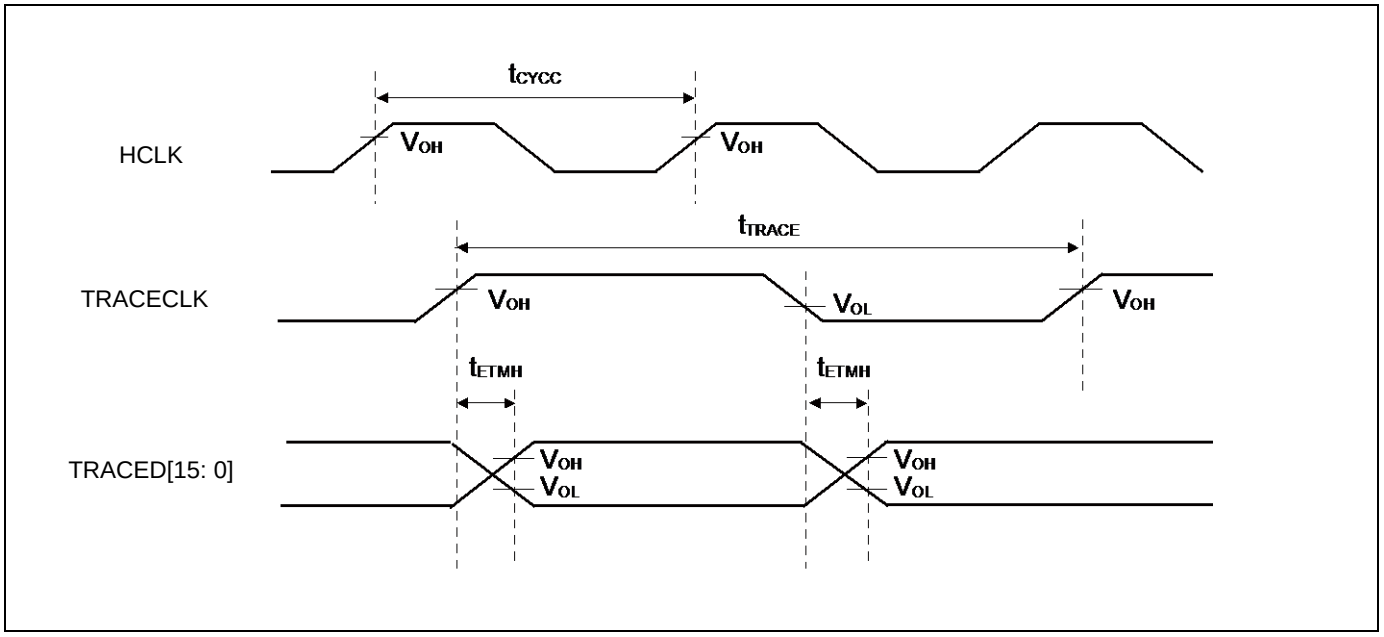
12.4.17 ETM/ HTM Timing

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Data hold	t_{ETMH}	TRACECLK, TRACED[15: 0]	$V_{CC} \geq 4.5$ V	2	9	ns	
			$V_{CC} < 4.5$ V	2	15		
TRACECLK frequency	$1/t_{TRACE}$	TRACECLK	$V_{CC} \geq 4.5$ V		50	MHz	
			$V_{CC} < 4.5$ V		32	MHz	
TRACECLK clock cycle	t_{TRACE}		$V_{CC} \geq 4.5$ V	20	-	ns	
			$V_{CC} < 4.5$ V	31.25	-	ns	

Note:

- *When the external load capacitance C_L = 30 pF.*



12.4.20 High-Speed Quad SPI Timing

(V_{CC} = 2.7V to 3.6V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Serial clock frequency	t_{SCYCM}	Q_SCK_0	C_L = 15 pF, V_{CC} = 3.0 to 3.6V	-	66	MHz	*1
			C_L = 30 pF	-	50	MHz	*2
Enabled CS→ CLK Starting Time (mode0/mode2)	$t_{OSLSK02}$	Q_SCK_0, Q_CS0_0, Q_CS1_0, Q_CS2_0	C_L = 30 pF	$1.5 \times t_{SCYCM}$ - 5	-	ns	
Enabled CS→ CLK Starting Time (mode1/mode3)	$t_{OSLSK13}$			t_{SCYCM} - 5	-	ns	
CLK Last→ Disabled CS Time (mode0/mode2)	$t_{OSKSL02}$			t_{SCYCM}	-	ns	
CLK Last→ Disabled CS Time (mode1/mode3)	$t_{OSKSL13}$			$1.5 \times t_{SCYCM}$	-	ns	
SIO Data output time	t_{OSDAT}	Q_SCK_0, Q_IO0_0, Q_IO1_0, Q_IO2_0, Q_IO3_0	C_L = 15 pF, V_{CC} = 3.0 to 3.6V	0	5	ns	
			C_L = 30 pF	0	5		
SIO Setup	t_{DSSET}		C_L = 30 pF	3	-	ns	*1
				10	-		*2
SIO Hold	t_{SDHOLD}		C_L = 30 pF	$0.5 \times t_{SCYCM}$	-	ns	

*1: When RTM = 1 and mode = 0, 1, 3

*2: When RTM = 1 and mode = 2 or RTM = 0 and mode = 0, 1, 2, 3

Notes:

- *See Chapter8-3: High-Speed Quad SPI controller in FM4 Family Peripheral Manual Communication Macro Part (002-04862) for the detail of RTM mode.*
- *When using High-Speed Quad SPI, please set PDSR register to set the pin drive capability for V_{CC} = 3V. See Chapter12: I/O Port in FM4 Family Peripheral Manual Main Part (002-04856) for the details.*

12.11 Standby Recovery Time

12.11.1 Recovery cause: Interrupt/WKUP

The time from the interrupt occurring to the time of program operation start is shown.

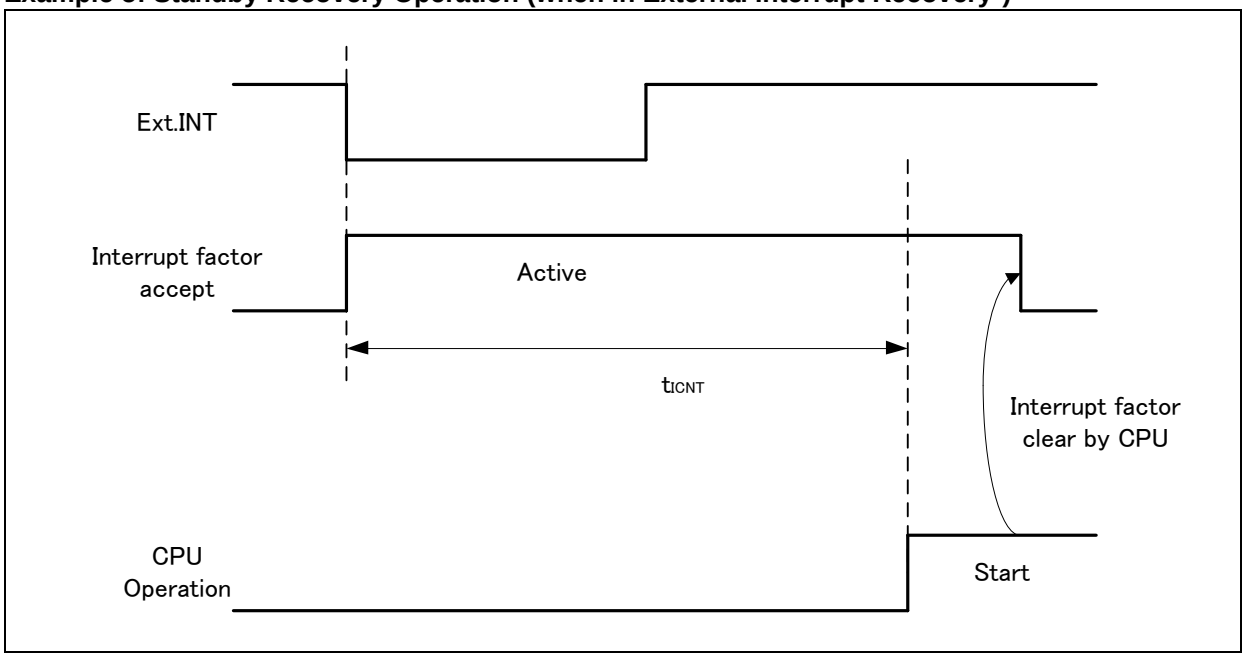
Recovery Count Time

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Value		Unit	Remarks
		Typ	Max*		
Sleep mode	t_{ICNT}	HCLK×1		µs	
High-speed CR Timer mode Main Timer mode PLL Timer mode		40	80	µs	
Low-speed CR Timer mode		450	900	µs	
Sub Timer mode		896	1136	µs	
RTC mode Stop mode (High-speed CR/Main/PLL Run mode return)		316	581	µs	
RTC mode Stop mode (Low-speed CR/sub Run mode return)		270	540	µs	
Deep Standby RTC mode with RAM retention		365	667	µs	without RAM retention
Deep Standby Stop mode with RAM retention		365	667	µs	with RAM retention

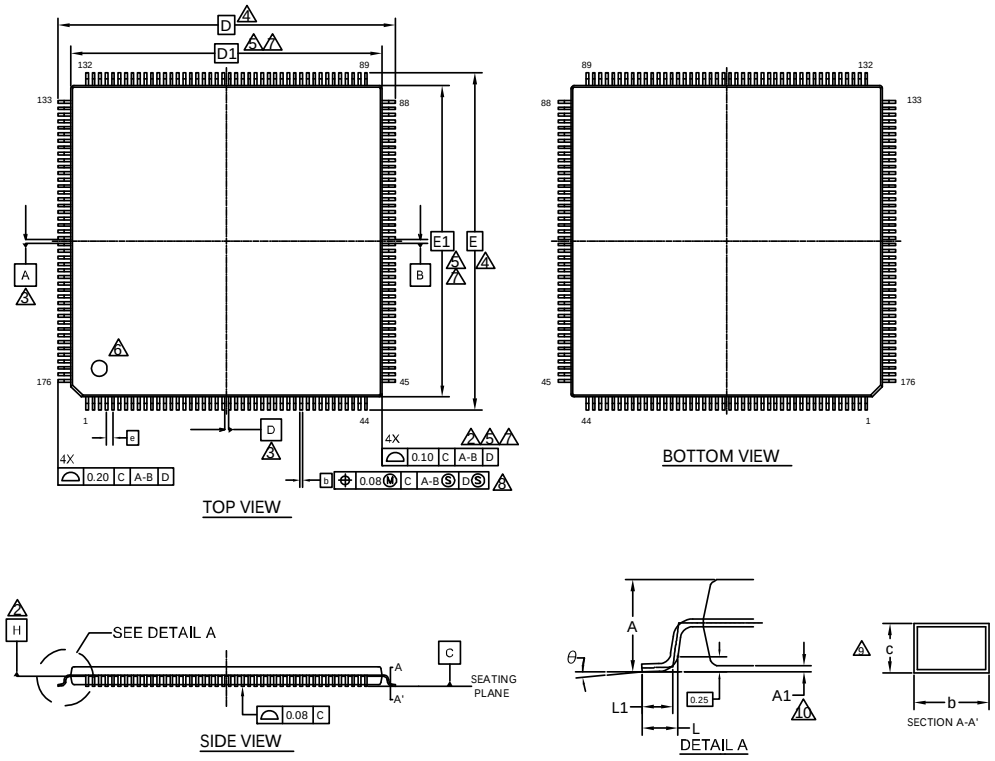
*: The maximum value depends on the built-in CR accuracy.

Example of Standby Recovery Operation (when in External Interrupt Recovery*)



*: External interrupt is set to detecting fall edge.

Package Type	Package Code
LQFP 176	LQP 176



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.05	—	0.15
b	0.17	0.22	0.27
c	0.09	—	0.20
D	26.00 BSC		
D1	24.00 BSC		
e	0.50 BSC		
E	26.00 BSC		
E1	24.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°	—	8°

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS, DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

002-15150 **

PACKAGE OUTLINE, 176 LEAD LQFP
24.0X24.0X1.7 MM LQP176 REV**